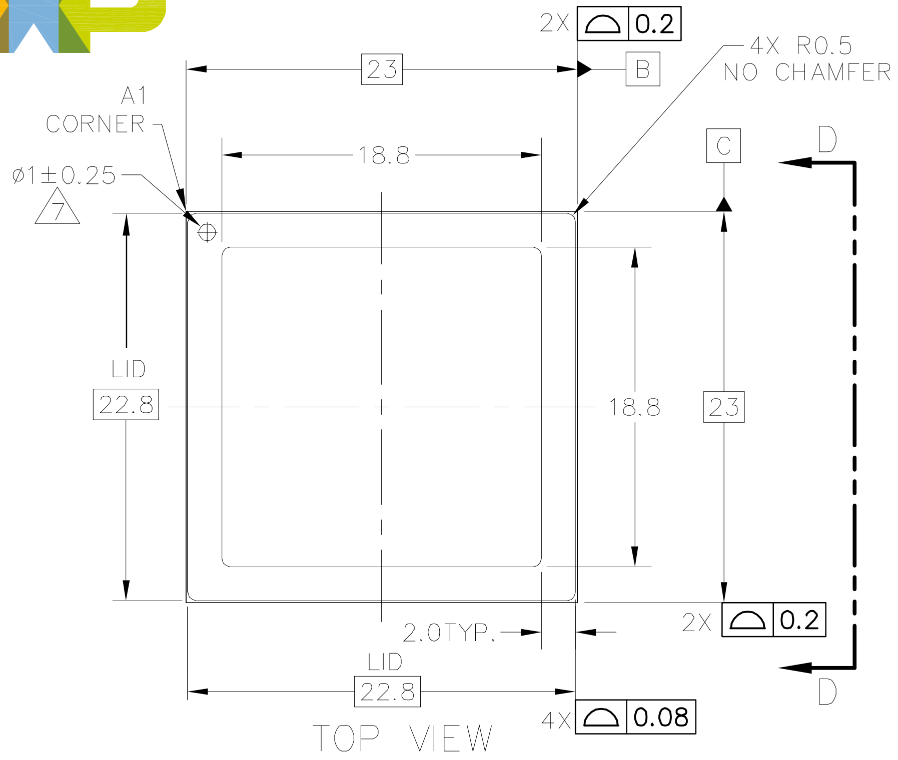

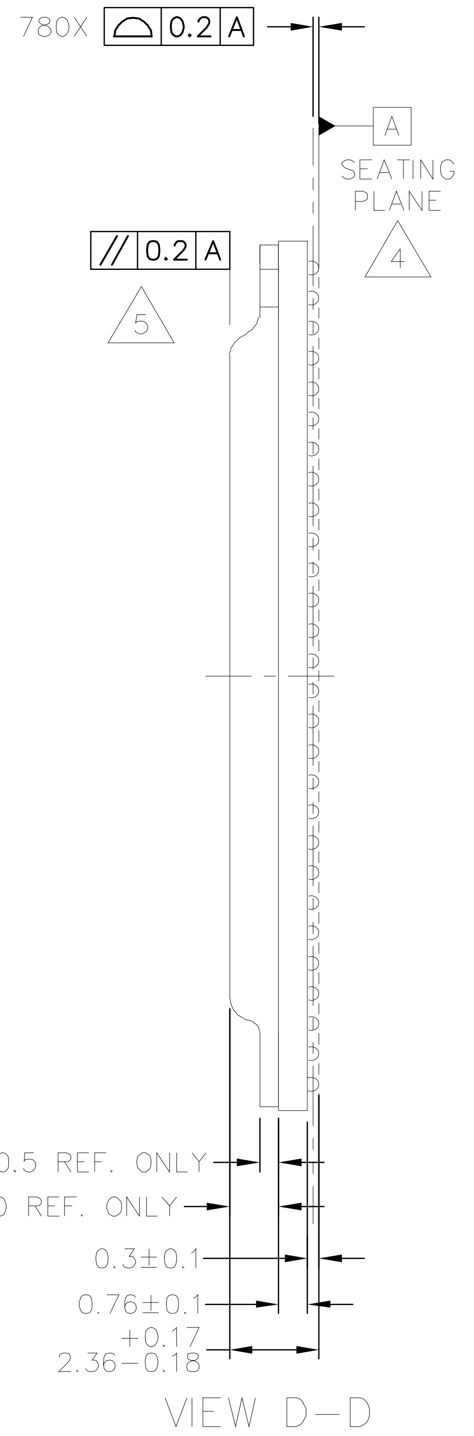

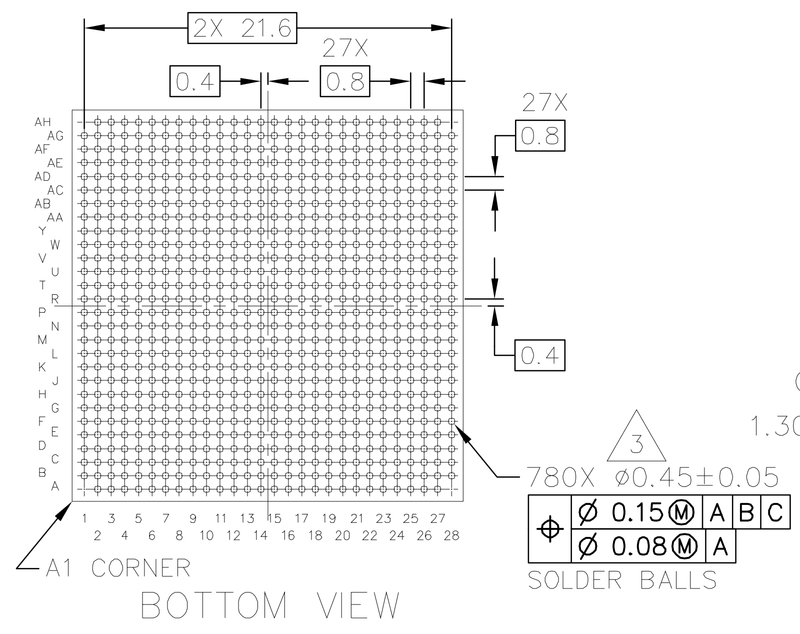

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MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: FC PBGA, WITH LID, 23 X 23 X 2.36 PKG, 0.8 MM PITCH, 780 I/O	DOCUMENT NO: 98ASA00254D REV: B
	STANDARD: NON−JEDEC
	SOT1639−1 07 JAN 2016

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.

7. PIN 1 THRU HOLE SHALL BE CENTERED WITHIN FOOT AREA.

8. 23.2MM MAXIMUM PACKAGE ASSEMBLY (LID + LAMINATE) X AND Y.

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